



# SOT361-2

TSSOP28, plastic, thin shrink small outline package; 28 terminals; 0.65 mm pitch; 4.4 mm x 9.7 mm x 0.95 mm body

7 January 2019

Package information

## 1 Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	TSSOP28
<b>Package style descriptive code</b>	TSSOP (thin shrink small outline package)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-153 AE
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	08-03-2016
<b>Manufacturer package code</b>	98ARS23923W

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	9.7	-	mm
package width	-	4.4	-	mm
package height	-	0.95	-	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	28	-	



TSSOP28, plastic, thin shrink small outline package; 28 terminals; 0.65 mm pitch; 4.4 mm x 9.7 mm x 0.95 mm body

2 Package outline

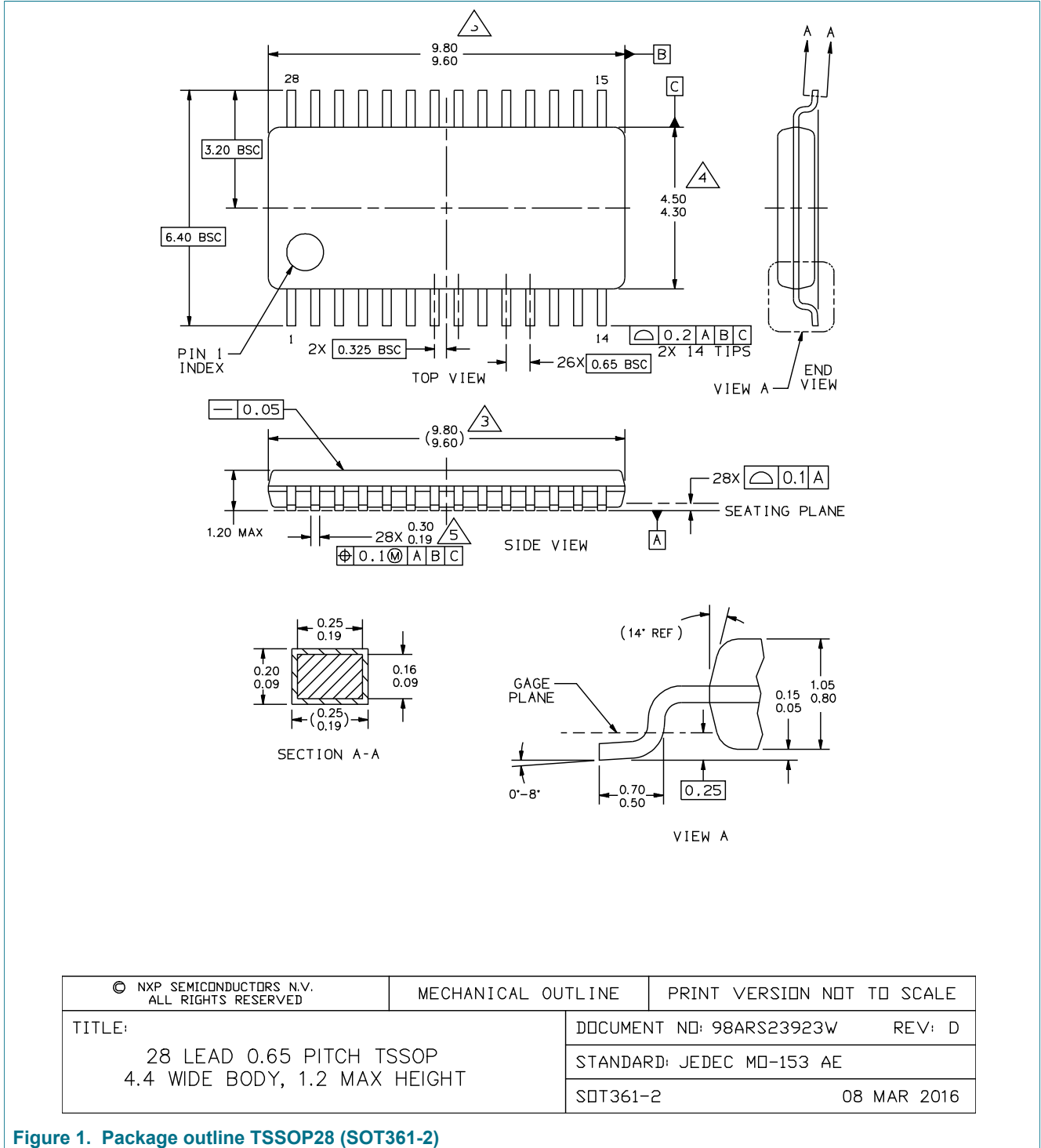


Figure 1. Package outline TSSOP28 (SOT361-2)

TSSOP28, plastic, thin shrink small outline package; 28 terminals; 0.65 mm pitch; 4.4 mm x 9.7 mm x 0.95 mm body

NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M-1994.
2. DIMENSIONS IN MILLIMETERS.
3. DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.15 PER END.
4. DIMENSION DOES NOT INCLUDE INTERLEAD FLASH OR MOLD PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.
5. DIMENSION DOES NOT INCLUDE DAM BAR PROTRUSIONS. DAM BAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.38.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 28 LEAD 0.65 PITCH TSSOP 4.4 WIDE BODY, 1.2 MAX HEIGHT	DOCUMENT NO: 98ARS23923W	REV: D
	STANDARD: JEDEC MO-153 AE	
	SOT361-2	08 MAR 2016

Figure 2. Package outline note TSSOP28 (SOT361-2)

### 3 Legal information

---

#### Disclaimers

**Limited warranty and liability** — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

**Right to make changes** — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

---

TSSOP28, plastic, thin shrink small outline package; 28 terminals; 0.65 mm pitch; 4.4 mm x 9.7 mm x 0.95 mm body

**Contents**

---

1 Package summary .....1  
2 Package outline .....2  
3 Legal information .....4